Compliant with IEC 62474/ D9.00

| Semiconductor Device Type: MS and UA (A3X) 008 MSOP 33/3mm Matter Tin Basic Substance CAS Number Sub-Component Weight mighant pp 29.43 (mg) Take Model Component Weight mighant pp 29.43 (mg) Take Model Component Weight mighant pp 29.44 (mg) Take Model Component Weight mighant pp 29.45 (mg) Take Model Component Weight mighant pp 29.46 (mg) Take Model Component Weight mighant pp 29.46 (mg) Take Model Component Weight mighant pp 29.45 (mg) Take Model Component Weight mighant pp 29.46 (mg) Take Model Component Weight mighant pp 29.46 (mg) Take Model Compon | MICROCHIP Semiconductor Device Turon MS and HA (ADV) 999 MSOR 202000 MSOR 202 | | | Termination Base Alloy: Copper Alloy (Cu) | | | Package Homogeneous Materials: 8.1 Electronics (e.g. pc boards, displays) | | | | JEDEC 97 Product Marking and/or Pkg. Labeling e3 |
|--|--|---|--|--|--|--|--|--|---|---|--|
| Baste Solutionation | Semiconductor Device Type | I WIS ATIO UA | | % Lotal | | | | | | | <u> </u> |
| ExpoyRearin Trade Secret Mod Compound 4,072 1,207 | Basic Substance | CAS Number | Sub-Component | Weight | mg/part | ppm | 20.43 | (mg) Total | Mold Compound | % ot Total Weight | 79.8 |
| Principle Resear | Silica, vitreous | 60676-86-0 | Mold Compound | 69.354 | 17.755 | 693,542 | | Silica, vitreous | 60676-86-0 | 86.91 | |
| Cathor Bisck 1333844 Mold Companed 0.247 0.063 2.744 Cathor Bisck 1323844 0.31 Cathor Bisck 1323844 0. | | | | | | | | Epoxy Resin | | | |
| Copper | | | | | | | | | | | |
| Siver 1, 740-224 Lead Frame 1, 200 0, 051 2, 200 Copper 7440-98 (9545 1) 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 | | | | | | | | Carbon Black | | | |
| Silver 7440-22-4 Leasf Frame 0.020 0.051 2.000 Copper 7440-05-8 56.54 Copper 7440-05-8 Coppe | Copper | | | | | | | | Total | 100.00 | |
| Procephorus 1772314-0 Lead Frame 0.003 0.003 131 Procephorus 1772314-0 Procephorus 1772314 | | | | | | 2,468 | 2.69 | (mg) Total | Lead Frame | % of Total Weight | 10.5 |
| Phosphorous 1723-14-0 Leaf Frame 0.009 0.002 87 Silver (Ag) 7440-22-4 Die Altach 0.558 0.144 5.625 Die Altach 0.005 0.007 1.005 Prosphorous 1723-14-0 0.00 0.00 0.007 Prosphorous 1723-14-0 0.00 0.00 0.007 Prosphorous 1723-14-0 0.00 0.00 0.00 0.00 0.00 0.00 0.00 0 | | | | | | | | Copper | 7440-50-8 | 95.54 | |
| Silver (A) 7440-224 Dea Attach 0.583 0.144 5.825 2 2cc 7440-864 0.13 Dely-objective of biophero-F 1520-86-3 De Attach 0.105 0.27 1.050 Period Dely-objective of biophero-F 1520-86-3 Dea Attach 0.006 0.014 0.056 0.014 | | | | | | | | | | | |
| Modified Epoys Resin 13561-685 Die Attach 0.105 0.027 1,050 Dighychylether of bisphenol-F 54,0508-68 Die Attach 0.026 0.014 553 Modified Armine 827-48-0 Die Attach 0.026 0.007 263 0.19 (mg) Total Die Attach 0.026 Modified Armine 827-48-0 Die Attach 0.026 0.007 263 0.19 (mg) Total Die Attach 0.026 0.007 Modified Armine 0.026 Die Attach 0.026 0.007 263 0.19 (mg) Total Die Attach 0.026 0.007 Modified Armine 0.026 Die Attach 0.026 0.007 263 0.19 (mg) Total Die Attach 0.026 0.007 0.008 Modified Armine 0.026 Die Attach 0.008 0.007 263 0.19 (mg) Total 0.008 0.007 0.008 0.007 0.008 0.009 0.008 0.009 0.008 0.009 | | | | | | | | Silver | | | |
| Dighycitylether of bisphenol-F 5428-63-8 Die Attach 0.056 0.074 553 0.19 (mg) Total Die Attach 50.076 0.75 0.050 | | | | | | | | Zinc | | | |
| Modified Armine 827-45-0 Die Attach 0.028 0.007 253 0.19 (mg) Total Die Attach 5.6 Total Weight 0.75 | Modified Epoxy Resin | 13561-08-5 | Die Attach | 0.105 | 0.027 | 1,050 | | Phosphorous | 7723-14-0 | 0.08 | |
| Silcon 1744-021-3 Chip (Die) 75.000 19.20 175.000 19.20 175.000 19.20 175.000 19.20 175.000 19.20 175.000 19.20 19 | Diglycidylether of bisphenol-F | 54208-63-8 | Die Attach | 0.056 | 0.014 | 563 | | | Total | 100.00 | |
| Copper 7440-50-8 Wire Bond palladium contant copper (CuPG) 0.197 0.050 1.955 Palladium 7440-51-5 Pairup on external less grows Marie Tin / 2000 2.560 1.0650 Tin 7440-51-5 Pairup on external less grows Marie Tin / 2000 2.560 1.000,000 Total (2000 2.560 1.000,000 2.560 1.000,000 Total (2000 2.560 2.500 1.000,000 Total (2000 2.560 2.500 2.500 2.500 2.500 2.500 Total (2000 2.560 2.500 2.500 2.500 2.500 Total (2000 2.560 2.500 2.500 2.500 2.500 2.500 2.500 Total (2000 2.560 2.500 2. | Modified Amine | 827-43-0 | Die Attach | 0.026 | 0.007 | 263 | 0.19 | (mg) Total | Die Attach | % of Total Weight | 0.75 |
| Palladum 7440-05-3 Wire Bond palladum coated copper (CuPd) 0.004 0.001 35 Modified Annu 827-43-0 4 100.00 1 100 | Silicon | 7440-21-3 | Chip (Die) | 7.500 | 1.920 | 75,000 | | Silver (Ag) | 7440-22-4 | 75 | |
| Tin (7440-315 Plarty on external aboles (pre) - Matte Tr / amnealed at 150°C tor 1 tow 1.250 0.320 1.2500 O.0.256 g Total Mass O.0.256 g Total Mass | Copper | 7440-50-8 | Wire Bond palladium coated copper (CuPd) | 0.197 | 0.050 | 1,965 | | Modified Epoxy Resin | 13561-08-5 | 14 | |
| TOTALS: 100.00 25.60 1,000,000 O.0256 g Total Mass emiconductor device and its homogenous materials comply with EU Directives: 2002/95/EC (27 January 2003) & Directive 2011/65/EU (08 June 2011) and 2015/663/EU (31 March and 2002/55/EC (16-d-L-Life Vehicles (ELV) without exemption (zero) liance with the above EU Directives has been verified via internal design controls, supplier declarations, and /or analytical test data. **Total** 1.92 | Palladium | 7440-05-3 | Wire Bond palladium coated copper (CuPd) | 0.004 | 0.001 | 35 | D | iglycidylether of bisphenol-F | 54208-63-8 | 8 | |
| Doped Silicon Total (mg) Chip (Die) % of Total Weight 7.5 microductor device and its homogenous materials comply with EU Directives: 2002/95/EC (27 January 2003) & Directive 2011/85/EU (08 June 2011) and 2015/85/EU (31 March and 2002/59/EC (End-of-Life Vehicles (ELV) without exemption (zero) Iance with the above EU Directives has been verified via internal design controls, supplier declarations, and for analytical test data. In the list above, the chemical substance is NOT an intentional ingredient in the semiconductor device and, to the best of Microchip Technology corated's knowledge and belief as of the date of this document, there is no credible reason to believe that the unavoidable impurity concentration of the chemical substance, if not below the threshold of regulatory concern for any regulatory scheme world-wide. Ing compounds used by Microchip meet the UL94 V0 flammability standard for plastics. You can access the UL iQTM family of databases to obtain a test report at ul.com/global/eng/pages/offerings/industries/chemicals/plastics/ Internation is not the protected from disclosure as trade secrets and some longer of the secret only and the secret to the best of its knowledge and belief, as of the date listed in this form. Microchip Technology incorporated cannot guarantee the eteress and accuracy of data in this form because weight of these parts and the average weight of a reage provided in Material Safety Data Sheets provided by a was material suppliers. But in this form because weight of these parts and the average weight of a reage provide of un was in this form because weight of these parts and the average weight of a relicipated significant totic metals components. These estimates do not et race levels of dopants, metals, and non-metal materials contained within silicon devices (silicon IC) in the finished parts. In this formation is often protected from disclosure as trade secrets and some information may not have been provided by Microchip Technology incorporated date is the secret or mate | Tin | 7440-31-5 | Plating on external leads (pins) - Matte Tin / annealed at 150°C for 1 hour | 1.250 | 0.320 | 12,500 | | Modified Amine | 827-43-0 | 4 | |
| miconductor device and its homogenous materials comply with EU Directives: 2002/85/EC (27 January 2003) & Directive 2011/85/EU (08 June 2011) and 2015/863/EU (31 March do 2012/53/EC (End-of-Life Vehicles (ELV) without exemption (zero) ance with the above EU Directives has been verified via internal design controls, supplier declarations, and /or analytical test data. mical substance is absent from the list above, the chemical substance is NOT an intentional ingredient in the semiconductor device and, to the best of Microchip Technology valed is knowledge and belief as of the date of this document, there is no credible reason to believe that the unavoidable impurity concentration of the chemical substance, if not below the threshold of regulatory concern for any regulatory scheme world-wide. g compounds used by Microchip meet the U.94 V0 flammability standard for plastics. You can access the U. IQTM family of databases to obtain a test report at Loon/global/eng/pages/offerings/industries/chemicals/plastics/ stective "tubes" in which the specific product is shipped are made from polyvinyl chloride (PVC) plastic. "Window envelopes" used to hold the packing slip on the outer box tain "reels" may be made from PVC plastic. Total Total Total Total 100.00 Wire Bond-Copper, palladium Copper (7440-50-8) 98 Loon/global/eng/pages/offerings/industries/chemicals/plastics/ steptive "tubes" in which the specific product is shipped are made from polyvinyl chloride (PVC) plastic. "Window envelopes" used to hold the packing slip on the outer box tain "reels" may be made from PVC plastic. Total Total Total 100.00 Total Total 100.00 Palladium 7440-05-3 2 Total 100.00 Total Weight 2-40-50-8 98 Loon/global/pages/offerings/industries/chemicals/plastics/ Total 100.00 Total Total 100.00 Total Weight 100.00 Total Total 100.00 Total Total Total 1 | | • | TOTALS: | 100.000 | 25.600 | 1,000,000 | | | Total | 100.00 | |
| miconductor device and its homogenous materials comply with EU Directives: 2002/85/EC (27 January 2003) & Directive 2011/85/EU (08 June 2011) and 2015/863/EU (31 March do 2012/53/EC (End-of-Life Vehicles (ELV) without exemption (zero) ance with the above EU Directives has been verified via internal design controls, supplier declarations, and /or analytical test data. mical substance is absent from the list above, the chemical substance is NOT an intentional ingredient in the semiconductor device and, to the best of Microchip Technology valed is knowledge and belief as of the date of this document, there is no credible reason to believe that the unavoidable impurity concentration of the chemical substance, if not below the threshold of regulatory concern for any regulatory scheme world-wide. g compounds used by Microchip meet the U.94 V0 flammability standard for plastics. You can access the U. IQTM family of databases to obtain a test report at Loon/global/eng/pages/offerings/industries/chemicals/plastics/ stective "tubes" in which the specific product is shipped are made from polyvinyl chloride (PVC) plastic. "Window envelopes" used to hold the packing slip on the outer box tain "reels" may be made from PVC plastic. Total Total Total Total 100.00 Wire Bond-Copper, palladium Copper (7440-50-8) 98 Loon/global/eng/pages/offerings/industries/chemicals/plastics/ steptive "tubes" in which the specific product is shipped are made from polyvinyl chloride (PVC) plastic. "Window envelopes" used to hold the packing slip on the outer box tain "reels" may be made from PVC plastic. Total Total Total 100.00 Total Total 100.00 Palladium 7440-05-3 2 Total 100.00 Total Weight 2-40-50-8 98 Loon/global/pages/offerings/industries/chemicals/plastics/ Total 100.00 Total Total 100.00 Total Weight 100.00 Total Total 100.00 Total Total Total 1 | | 0.0256 | a Total Mass | | | · · · - | 1 02 | | | | |
| compounds used by Microchip meet the UL94 V0 flammability standard for plastics. You can access the UL iQTM family of databases to obtain a test report at com/global/eng/pages/offerings/industries/chemicals/plastics/ tective "tubes" in which the specific product is shipped are made from polyvinyl chloride (PVC) plastic. "Window envelopes" used to hold the packing slip on the outer box tain "reels" may be made from PVC plastic. Total 100.00 Palladium 7440-05-3 2 In Total 100.00 Total 100.00 Total 100.00 Palladium 7440-05-3 2 In Total 100.00 Total 10 | nd 2002/53/EC (End-of-Life Vehicles (ELV) without exemption | vith EU Directives n (zero) | 2002/95/EC (27 January 2003) & Directive 2011/65/EU (08 | 3 June 2011) a | and 2015/863/E | U (31 March | 1.92 | | 7440-21-3 | 100 | 7.5 |
| ip Technology Incorporated believes the information in this form concerning substances restricted by RoHS in Microchip Technology Incorporated's semiconductor devices in ginal packing materials is true and correct to the best of its knowledge and belief, as of the date listed in this form. Microchip Technology Incorporated cannot guarantee the eness and accuracy of data in this form because it has been compiled based on the ranges provided in Material Safety Data Sheets provided by raw material suppliers. It information is often protected from disclosure as trade secrets and some information may not have been provided by subcontract assemblers and raw material suppliers. It is is often protected from disclosure as trade secrets and the average weight of anticipated significant toxic metals components. These estimates do not trace levels of dopants, metals, and non-metal materials contained within silicon devices (silicon IC) in the finished parts. In Total 100.00 In Total 100 | ed 2002/53/EC (End-of-Life Vehicles (ELV) without exemption ince with the above EU Directives has been verified via intendical substance is absent from the list above, the chemical rated's knowledge and belief as of the date of this documer | with EU Directives n (zero) nal design contro substance is NOT t, there is no credi | 2002/95/EC (27 January 2003) & Directive 2011/65/EU (08 is, supplier declarations, and /or analytical test data. an intentional ingredient in the semiconductor device and, ble reason to believe that the unavoidable impurity concer | to the best o | of Microchip Te | chnology | | Doped Silicon | 7440-21-3 Total Wire Bond - Copper, palladium | 100 | |
| ip Technology Incorporated believes the information in this form concerning substances restricted by RoHS in Microchip Technology Incorporated's semiconductor devices in glinal packing materials is true and correct to the best of its knowledge and belief, as of the date listed in this form. Microchip Technology Incorporated cannot guarantee the teness and accuracy of data in this form because it has been compiled based on the ranges provided in Material Safety Data Sheets provided by raw material suppliers. In information is often protected from disclosure as trade secrets and some information may not have been provided by subcontract assemblers and raw material suppliers. It is provided only as estimates of the average weight of these parts and the average weight of anticipated significant toxic metals components. These estimates do not trace levels of dopants, metals, and non-metal materials contained within silicon devices (silicon IC) in the finished parts. In Technology Incorporated does not provide any warranty, express or implied, with respect to the information provided in this declaration. The exclusive, limited product less provided by Microchip Technology Incorporated and its subsidiaries are contained in Microchip's standard terms and conditions of sale. These are provided in Microchip's one, sales order acknowledgement, and invoices. In Judician and Judician are contained in Microchip's standard terms and conditions of sale. These are provided in Microchip's one at a result of the users' reliance on the information in Material Content Declarations (MCD) or independent third party test reports (SGS) or Judician and Judician a | nd 2002/53/EC (End-of-Life Vehicles (ELV) without exemption ance with the above EU Directives has been verified via intendical substance is absent from the list above, the chemical rated's knowledge and belief as of the date of this document to below the threshold of regulatory concern for any regular compounds used by Microchip meet the UL94 V0 flammab | with EU Directives in (zero) mal design contro substance is NOT t, there is no credi tory scheme work ility standard for p | 2002/95/EC (27 January 2003) & Directive 2011/65/EU (08 is, supplier declarations, and /or analytical test data. an intentional ingredient in the semiconductor device and, ble reason to believe that the unavoidable impurity concert-wide. | to the best o | of Microchip Te e chemical sub | chnology | | Doped Silicon (mg) Total | 7440-21-3 Total Wire Bond - Copper, palladium coated (CuPd) | 100 100.00 % of Total Weight | |
| ties provided by Microchip Technology Incorporated and its subsidiaries are contained in Microchip's standard terms and conditions of sale. These are provided in Microchip's one, sales order acknowledgement, and invoices. (mg) Total leads (pins) - Matte Tin / annealed at 150°C for 1 hour 1.25 hip disclaims any duty to notify users of updates or changes to Material Content Declarations and shall not be liable for any damages, direct or indirect, consequential or itse, suffered by users or third parties as a result of the users' reliance on the information in Material Content Declarations (MCD) or independent third party test reports (SGS) or Certificate of Compliance for semiconductor products. | and 2002/53/EC (End-of-Life Vehicles (ELV) without exemption ince with the above EU Directives has been verified via interprise and ince with the above EU Directives has been verified via interprise and belief as of the date of this documer not below the threshold of regulatory concern for any regular groups and see a compounds used by Microchip meet the UL94 V0 flammabil.com/global/eng/pages/offerings/industries/chemicals/plast offective "tubes" in which the specific product is shipped are | with EU Directives in (zero) rnal design contro substance is NOT t, there is no credi tory scheme work illity standard for p cs/ | 2002/95/EC (27 January 2003) & Directive 2011/65/EU (08 is, supplier declarations, and /or analytical test data. an intentional ingredient in the semiconductor device and, ble reason to believe that the unavoidable impurity concerd-wide. lastics. You can access the UL iQTM family of databases to | to the best on tration of the obtain a tes | of Microchip Te e chemical sub ot report at | chnology stance, if | | Doped Silicon (mg) Total Copper | 7440-21-3 Total Wire Bond - Copper, palladium coated (CuPd) 7440-50-8 | 100 100.00 % of Total Weight | |
| rise, suffered by users or third parties as a result of the users' reliance on the information in Material Content Declarations (MCD) or independent third party test reports (SGS) or Tin 7440-31-5 100.00 Certificate of Compliance for semiconductor products. | and 2002/53/EC (End-of-Life Vehicles (ELV) without exemption liance with the above EU Directives has been verified via intermical substance is absent from the list above, the chemical orated's knowledge and belief as of the date of this documer not below the threshold of regulatory concern for any regular grompounds used by Microchip meet the UL94 V0 flammab al.com/global/eng/pages/offerings/industries/chemicals/plast otective "tubes" in which the specific product is shipped are entain "reels" may be made from PVC plastic. Thip Technology Incorporated believes the information in this riginal packing materials is true and correct to the best of its eteness and accuracy of data in this form because it has bee er information is often protected from disclosure as trade se lation is provided only as estimates of the average weight of | with EU Directives In (zero) rnal design contro substance is NOT t, there is no credi tory scheme work tility standard for p cs/ made from polyvi form concerning knowledge and be n compiled based rets and some inf hese parts and the | 2002/95/EC (27 January 2003) & Directive 2011/65/EU (08 is, supplier declarations, and /or analytical test data. an intentional ingredient in the semiconductor device and, ble reason to believe that the unavoidable impurity concert-wide. lastics. You can access the UL iQTM family of databases to a constant of the co | to the best o ntration of the poblatin a tes old the packin acorporated's y Incorporate dided by raw r emblers and r | of Microchip Te e chemical sub it report at ig slip on the o is semiconducted cannot guar material suppli raw material su | chnology stance, if uter box or devices in antee the errs. | | Doped Silicon (mg) Total Copper | 7440-21-3 Total Wire Bond - Copper, palladium coated (CuPd) 7440-50-8 7440-05-3 | 100 100.00 % of Total Weight 98 | 0.2 |
| nbled package referenced above is EU REACH compliant based on the latest SVHC candidate list of ECHA which can be found at | and 2002/53/EC (End-of-Life Vehicles (ELV) without exemption liance with the above EU Directives has been verified via intermical substance is absent from the list above, the chemical corated's knowledge and belief as of the date of this documer is not below the threshold of regulatory concern for any regulary compounds used by Microchip meet the UL94 V0 flammab ul.com/global/eng/pages/offerings/industries/chemicals/plast corective "tubes" in which the specific product is shipped are entain "reels" may be made from PVC plastic. This Technology Incorporated believes the information in this riginal packing materials is true and correct to the best of its eteness and accuracy of data in this form because it has bee ier information is often protected from disclosure as trade se lation is provided only as estimates of the average weight of e trace levels of dopants, metals, and non-metal materials cochip Technology Incorporated and its tions, sales order acknowledgement, and invoices. | with EU Directives in (zero) real design contro t, there is no credi tory scheme work flitty standard for p cs/ made from polyvi form concerning knowledge and be rets and some inf hese parts and th tained within silic express or implie subsidiaries are co | 2002/95/EC (27 January 2003) & Directive 2011/65/EU (06 is, supplier declarations, and /or analytical test data. an intentional ingredient in the semiconductor device and, ble reason to believe that the unavoidable impurity concerd-wide. Ilastics. You can access the UL iQTM family of databases to have a constant of the control of the | to the best o ntration of the poblain a tes old the packin accorporated's y Incorporate ided by raw r emblers and r inponents. Th | of Microchip Te e chemical sub at report at ag slip on the o a semiconduct ed cannot guar material suppli raw material st nese estimates usive, limited p re provided in l | chnology stance, if uter box or devices in antee the ers. uppliers. do not | 0.05 | Doped Silicon (mg) Total Copper Palladium | 7440-21-3 Total Wire Bond - Copper, palladium coated (CuPd) 7440-50-8 7440-05-3 Total Plating on external leads (pins) - Matte Tin / annealed at 150°C for 1 | 98 2 | 0.2 |
| | and 2002/53/EC (End-of-Life Vehicles (ELV) without exemption iliance with the above EU Directives has been verified via interemical substance is absent from the list above, the chemical porated's knowledge and belief as of the date of this documer is not below the threshold of regulatory concern for any regulating compounds used by Microchip meet the UL94 V0 flammab ul.com/global/eng/pages/offerings/industries/chemicals/plast protective "tubes" in which the specific product is shipped are entain "reels" may be made from PVC plastic. This Technology Incorporated believes the information in this priginal packing materials is true and correct to the best of its leteness and accuracy of data in this form because it has been iter information is often protected from disclosure as trade senation is provided only as estimates of the average weight of let trace levels of dopants, metals, and non-metal materials concluded the provided by Microchip Technology Incorporated does not provide any warranty thies provided by Microchip Technology Incorporated and its tions, sales order acknowledgement, and invoices. | with EU Directives in (zero) rnal design contro substance is NOT t, there is no credi tory scheme work ility standard for p cs/ made from polyvi form concerning knowledge and be in compiled based crets and some inf these parts and th intained within silic express or implie subsidiaries are c to Material Conte | 2002/95/EC (27 January 2003) & Directive 2011/65/EU (06 is, supplier declarations, and /or analytical test data. In intentional ingredient in the semiconductor device and, ble reason to believe that the unavoidable impurity concert-wide. Ilastics. You can access the UL iQTM family of databases to a concert in the intentional process. In the intentional process with the intentional process are setticted by RoHS in Microchip Technology Ir lief, as of the date listed in this form. Microchip Technology on the ranges provided in Material Safety Data Sheets process average weight of anticipated significant toxic metals coron devices (silicon IC) in the finished parts. In the intention of the information provided in this declarated that in this intention in Microchip's standard terms and conditions of the contentions and shall not be liable for any damages, dintentions and shall not be liable for any damages, dintentions in the intention in the intention in the liable for any damages, dintentions and shall not be liable for any damages, dintentions and shall not be liable for any damages, dintentions and shall not be liable for any damages, dintentions and shall not be liable for any damages, dintentions and shall not be liable for any damages, dintentions and shall not be liable for any damages, dintentions and shall not be liable for any damages, dintentions are seminary to the contention of the | to the best of the best of the best of the book of the packin accorporated's y Incorporated by raw remblers and reponents. The ion. The exclusive incorporate are considered to the best of the best o | of Microchip Te e chemical sub- st report at a g slip on the or a semiconducted cannot guar material supplicate material supplicate e provided in loct, consequent | chnology stance, if uter box or devices in antee the ers. do not product wicrochip's | 0.05 | Doped Silicon (mg) Total Copper Palladium (mg) Total | 7440-21-3 Total Wire Bond - Copper, palladium coated (CuPd) 7440-50-8 7440-05-3 Total Plating on external leads (pins) - Matte Tin / annealed at 150°C for 1 hour | 100 100.00 % of Total Weight 98 2 100.00 % of Total Weight 100.00 | 0.2 |

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